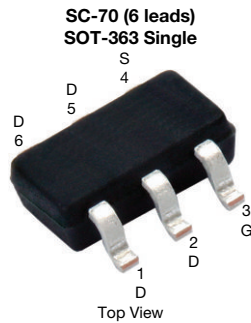


P-Channel 20 V (D-S) MOSFET



Marking Code: BUxx

PRODUCT SUMMARY	
V_{DS} (V)	-20
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -10$ V	0.035
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -4.5$ V	0.040
$R_{DS(on)}$ max. (Ω) at $V_{GS} = -2.5$ V	0.060
Q_g typ. (nC)	7.0
I_D (A) ^a	-3
Configuration	Single

ORDERING INFORMATION	
Package	SOT-363
Lead (Pb)-free and halogen-free	Si1425DH-T1-GE3

ABSOLUTE MAXIMUM RATINGS ($T_A = 25^\circ\text{C}$, unless otherwise noted)				
PARAMETER	SYMBOL	LIMIT	UNIT	
Drain-source voltage	V_{DS}	-20	V	
Gate-source voltage	V_{GS}	± 12		
Continuous drain current ($T_J = 150^\circ\text{C}$) ^a	$T_F = 25^\circ\text{C}$	-3 ^a	A	
	$T_F = 70^\circ\text{C}$	-3 ^a		
	$T_A = 25^\circ\text{C}$	-3 ^{a, b, c}		
	$T_A = 70^\circ\text{C}$	-3 ^{a, b, c}		
Pulsed drain current ($V_{GS} = 10$ V, $t = 100$ μs)	I_{DM}	-12		
Continuous source-drain diode current	$T_F = 25^\circ\text{C}$	-2.5	A	
	$T_A = 25^\circ\text{C}$	-1.4 ^{b, c}		
Maximum power dissipation ^a	$T_F = 25^\circ\text{C}$	2.8	W	
	$T_F = 70^\circ\text{C}$	1.8		
	$T_A = 25^\circ\text{C}$	1.6 ^{b, c}		
	$T_A = 70^\circ\text{C}$	1.0 ^{b, c}		
Operating junction and storage temperature range	T_J, T_{stg}	-55 to +150	$^\circ\text{C}$	

THERMAL RESISTANCE RATINGS					
PARAMETER		SYMBOL	TYPICAL	MAXIMUM	UNIT
Maximum junction-to-ambient ^{b, d}	$t \leq 5$ s	R_{thJA}	60	80	$^\circ\text{C/W}$
Maximum junction-to-foot (drain)	Steady state	R_{thJF}	34	45	

Notes

- Package limited
- Surface mounted on 1" x 1" FR4 board
- $t = 5$ s
- Maximum under steady state conditions is 125 $^\circ\text{C/W}$

FEATURES

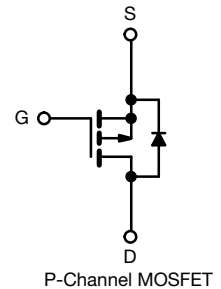
- TrenchFET[®] gen V p-channel MOSFET
- 100 % R_g and UIS tested
- Material categorization: for definitions of compliance please see www.vishay.com/doc?99912

APPLICATIONS

- Load switches
- DC/DC converters
- Power management
- LED backlighting



RoHS
COMPLIANT
HALOGEN
FREE



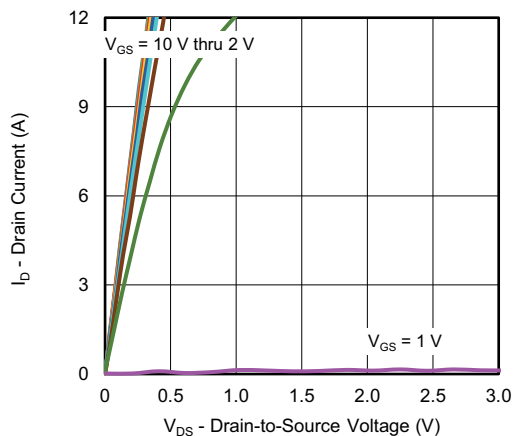
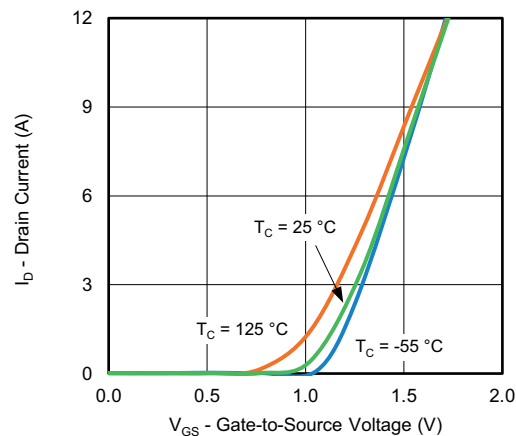
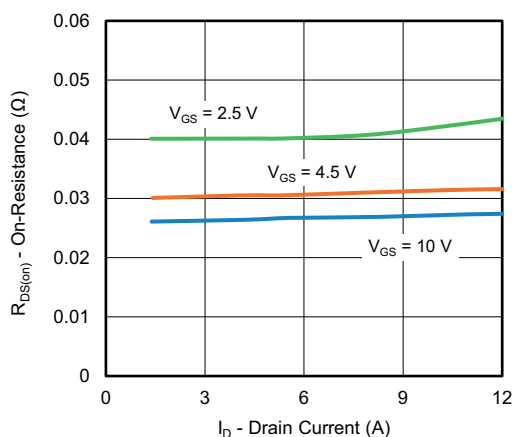
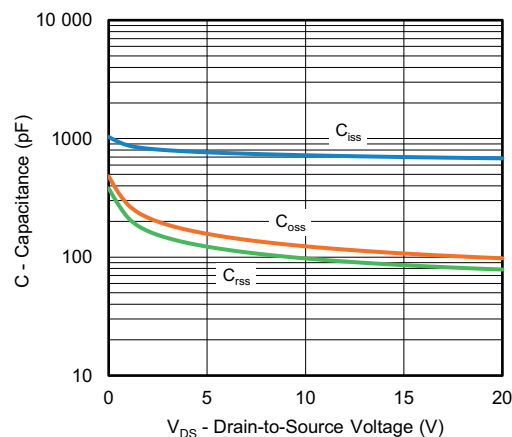
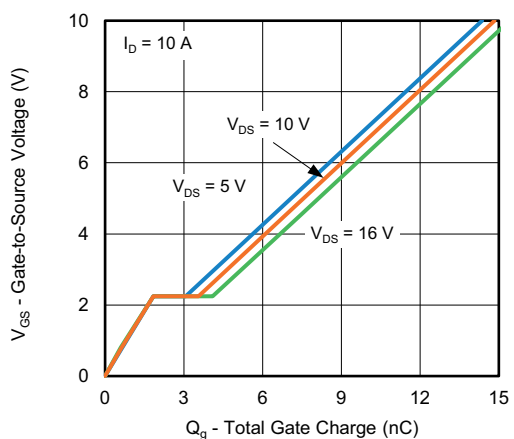
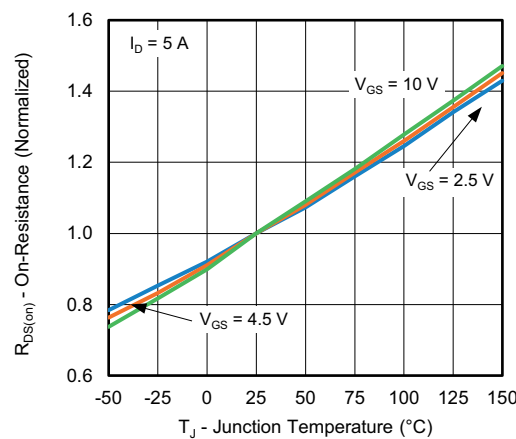


SPECIFICATIONS (T _J = 25 °C, unless otherwise noted)							
PARAMETER	SYMBOL	TEST CONDITIONS	MIN.	TYP.	MAX.	UNIT	
Static							
Drain-source breakdown voltage	V _{DS}	V _{GS} = 0 V, I _D = -250 μA	-20	-	-	V	
V _{DS} temperature coefficient	ΔV _{DS} /T _J	I _D = -10 mA	-	-14.2	-	mV/°C	
V _{GS(th)} temperature coefficient	ΔV _{GS(th)} /T _J	I _D = -250 μA	-	3.2	-		
Gate-source threshold voltage	V _{GS(th)}	V _{DS} = V _{GS} , I _D = -250 μA	-0.6	-	-1.5	V	
Gate-source leakage	I _{GSS}	V _{DS} = 0 V, V _{GS} = ± 20 V	-	-	± 100	nA	
Zero gate voltage drain current	I _{DSS}	V _{DS} = -20 V, V _{GS} = 0 V	-	-	-1	μA	
		V _{DS} = -20 V, V _{GS} = 0 V, T _J = 55 °C	-	-	-10		
Drain-source on-state resistance ^a	R _{DS(on)}	V _{GS} = -10 V, I _D = -5 A	-	0.027	0.035	Ω	
		V _{GS} = -4.5 V, I _D = -3 A	-	0.031	0.043		
		V _{GS} = -2.5 V, I _D = -2 A	-	0.040	0.060		
Forward transconductance	g _{fs}	V _{DS} = -10 V, I _D = -6 A	-	20	-	S	
Dynamic ^b							
Input capacitance	C _{iss}	V _{DS} = -10 V, V _{GS} = 0 V, f = 1 MHz	-	730	-	pF	
Output capacitance	C _{oss}		-	125	-		
Reverse transfer capacitance	C _{rss}		-	100	-		
Total gate charge	Q _g	V _{DS} = -10 V, V _{GS} = 10 V, I _D = -10 A	-	15	23	nC	
Gate-source charge	Q _{gs}	V _{DS} = -10 V, V _{GS} = 4.5 V, I _D = 2 A	-	7	11		
Gate-drain charge	Q _{gd}		-	1.8	-		
Gate resistance	R _g		-	1.8	-		
Turn-on delay time	t _{d(on)}	f = 1 MHz	1.3	6.5	13	Ω	
Rise time	t _r		V _{DD} = -10 V, R _L = 1 Ω I _D ≅ -10 A, V _{GEN} = -4.5 V, R _g = 1 Ω	-	12	25	ns
Turn-off delay time	t _{d(off)}			-	32	65	
Fall time	t _f			-	22	45	
Turn-on delay time	t _{d(on)}	V _{DD} = -10 V, R _L = 1 Ω I _D ≅ -10 A, V _{GEN} = -10 V, R _g = 1 Ω		-	10	20	
Rise time	t _r		-	7	15		
Turn-off delay time	t _{d(off)}		-	5	10		
Fall time	t _f		-	19	40		
Drain-Source Body Diode Characteristics							
Continous source-drain diode current	I _S	T _C = 25 °C	-	-	-2.5	A	
Pulse diode forward current ^a	I _{SM}		-	-	-12		
Body diode voltage	V _{SD}	I _S = -5 A, V _{GS} = 0 V	-	-0.85	-1.1	V	
Body diode reverse recovery charge	Q _{rr}	I _F = -10 A, dI/dt = 100 A/μs, T _J = 25 °C	-	2.5	5	nC	
Body diode reverse recovery time	t _{rr}		-	8	20	ns	
Reverse recovery fall time	t _a		-	5	-		
Reverse recovery rise time	t _b		-	3	-		

Notes

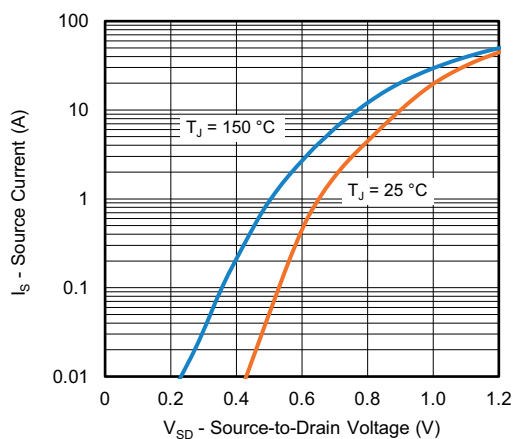
- a. Pulse test; pulse width $\leq 300\text{ }\mu\text{s}$, duty cycle $\leq 2\%$
b. Guaranteed by design, not subject to production testing

Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

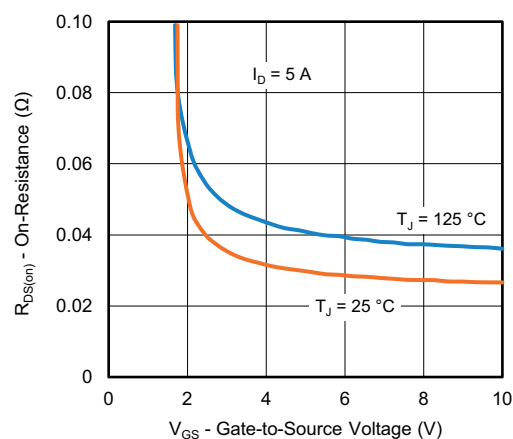
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)

Output Characteristics

Transfer Characteristics Curves vs. Temperature

On-Resistance vs. Drain Current

Capacitance

Gate Charge

On-Resistance vs. Junction Temperature



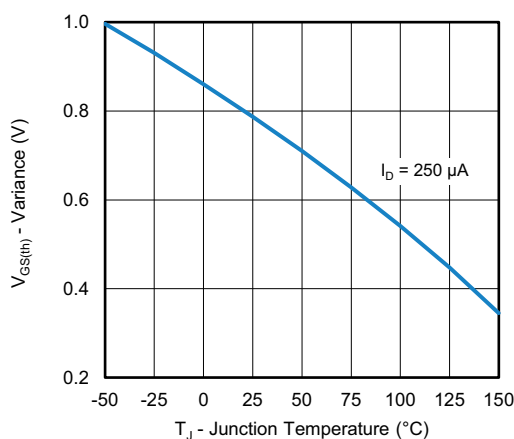
TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



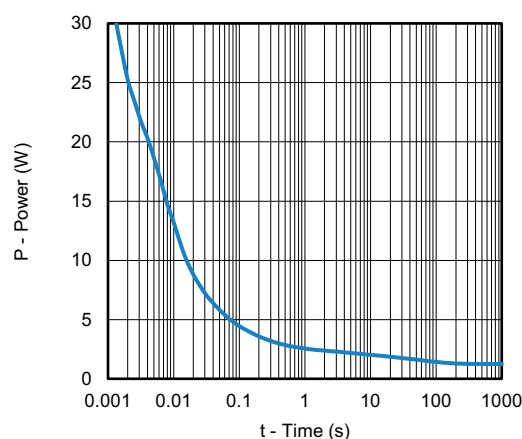
Source-Drain Diode Forward Voltage



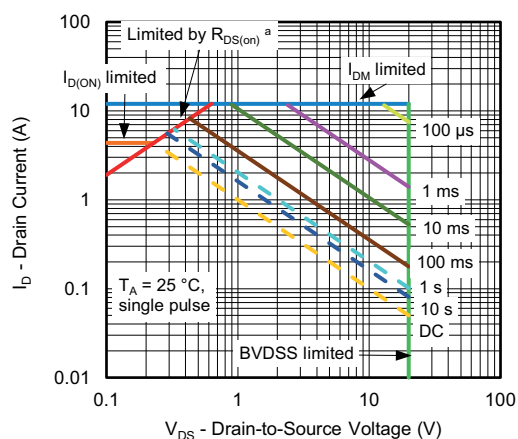
$R_{DS(on)}$ vs. V_{GS} vs. Temperature



Threshold Voltage



Single Pulse Power



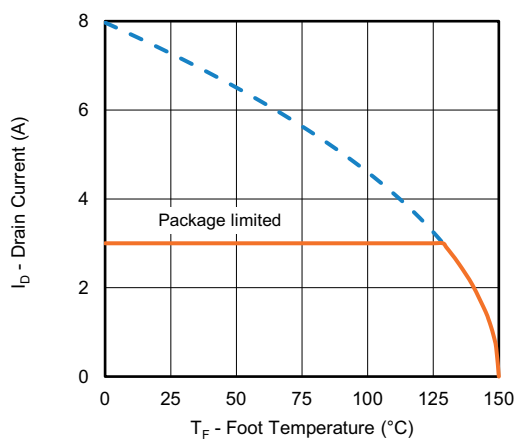
Safe Operating Area, Junction-to-Ambient

Note

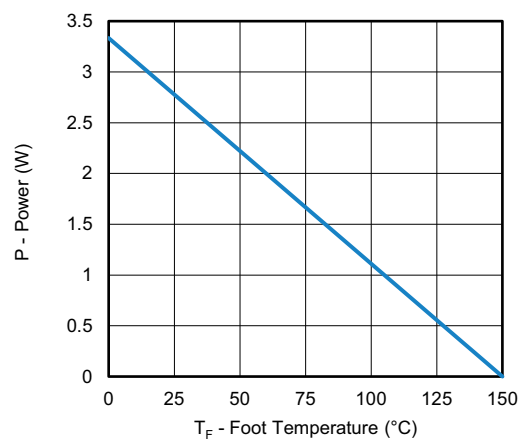
a. $V_{GS} >$ minimum V_{GS} at which $R_{DS(on)}$ is specified



TYPICAL CHARACTERISTICS ($T_A = 25^\circ\text{C}$, unless otherwise noted)



Current Derating ^a



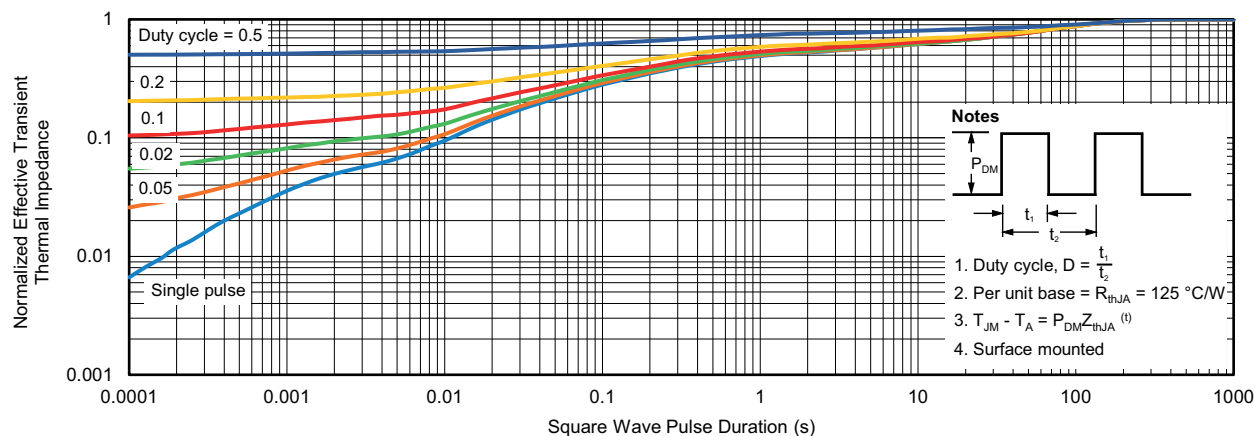
Power, Junction-to-Foot

Note

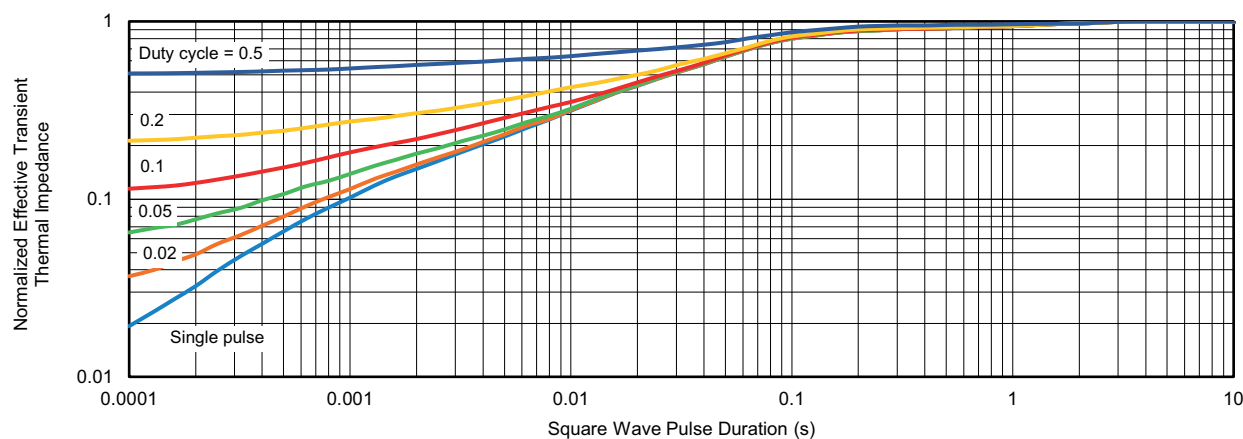
- a. The power dissipation P_D is based on T_J max. = 150°C , using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit



TYPICAL CHARACTERISTICS ($T_A = 25\text{ }^{\circ}\text{C}$, unless otherwise noted)



Normalized Thermal Transient Impedance, Junction-to-Ambient



Normalized Thermal Transient Impedance, Junction-to-Foot

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